

AMENDMENTS TO THE CLAIMS

1. canceled.
2. (currently amended) The method of claim ~~427~~, wherein steps A) and B) are carried out concurrently.
3. (currently amended) The method of claim ~~427~~, wherein steps A) and B) are carried out sequentially in any order.
4. (currently amended) The method of claim ~~427~~, further comprising: storing the polymeric material after step A) and before step C), or storing the adherend after step B) and before step C), or both.
5. (currently amended) The method of claim ~~427~~, further comprising repeating steps A), B), and C) one or more times.
6. (original) The method of claim 5, wherein steps A), B), and C) are repeated once to add a second adherend to the polymeric material.
7. (currently amended) The method of claim ~~427~~, wherein the polymeric material has a modulus of at least about 0.1 megaPascal.
8. (currently amended) The method of claim ~~427~~, wherein the polymeric material has a modulus of up to about 5 gigaPascals.
9. (original) The method of claim 8, wherein the polymeric material has a modulus of up to about 1 gigaPascal.

10. (original) The method of claim 9, wherein the polymeric material has a modulus of up to about 300 megaPascals.

11. (currently amended) The method of claim 12⁷, wherein the polymeric material comprises a thermoset material comprising a flexibilized epoxy or an elastomer.

12. (currently amended) The method of claim 12⁷, wherein the polymeric material comprises a thermoplastic material comprising a silicone-organic copolymer wax, a polyolefin, a polyimide, a phenolic, or combinations thereof.

13. (currently amended) The method of claim 12⁷, wherein the polymeric material comprises a silicone, an organic, a silicone-organic copolymer, or combinations thereof.

14. (currently amended) The method of claim 13, wherein A method comprising:
A) plasma treatment of a polymeric material, wherein the polymeric material
comprises a silicone and the silicone comprises a cured silicone resin, a cured silicone elastomer,
a cured silicone rubber, or a combination thereof,
B) plasma treatment of an adherend, and
C) thereafter contacting the polymeric material and the adherend;
thereby creating adhesion of the polymeric material and the adherend;
wherein the method is carried out during fabrication of an electronic device, an electronic
device package, a photonic device, or an optoelectronic device.

15. (original) The method of claim 13, wherein the organic comprises a cured organic resin, a cured organic elastomer, a cured organic polymer, or a combination thereof.

16. (currently amended) The method of claim 12⁷, wherein step A) and step B) are each independently carried out using a plasma treatment selected from corona discharge treatment, dielectric barrier discharge treatment, and glow discharge treatment.

17. (original) The method of claim 16, wherein the glow discharge treatment is carried out using plasma selected from low pressure glow discharge or atmospheric pressure glow discharge.

18. (currently amended) The method of claim ~~127~~, wherein step A) and step B) are each independently carried out at a pressure of up to about atmospheric pressure.

19. canceled.

20. (currently amended) The method of claim ~~127~~, wherein step A) and step B) are each independently carried out for a time of at least about 1 millisecond.

21. (currently amended) The method of claim ~~127~~, wherein step A) and step B) are each independently carried out for a time of up to about 30 minutes.

22. (currently amended) The method of claim ~~127~~, wherein step C) is carried out at a temperature of at least about 15 °C.

23. (currently amended) The method of claim ~~127~~, wherein step C) is carried out at a temperature of up to about 400 °C.

24. (currently amended) The method of claim ~~127~~, wherein step C) is carried out by applying pressure for a time of at least about 0.1 second.

25. (currently amended) The method of claim ~~127~~, wherein step C) is carried out by applying pressure for a time of up to about 12 hours.

26. (currently amended) A method comprising:

A) plasma treatment of a polymeric material for up to about 30 seconds,

B) plasma treatment of an adherend for up to about 30 minutes, and
C) thereafter contacting the polymeric material and the adherend;
thereby creating adhesion of the polymeric material and the adherend.

27. (currently amended) A method comprising:
A) plasma treatment of a polymeric material;
B) plasma treatment of an adherend;
wherein steps A) and B) are carried out using a gas comprising air, argon, carbon dioxide, helium, nitrogen, nitrous oxide, ozone, or combinations thereof; and
C) thereafter contacting the polymeric material and the adherend;
thereby creating adhesion of the polymeric material and the adherend.

28. canceled.

29. (currently amended) A method comprising:
A) plasma treatment of a polymeric material;
B) plasma treatment of a substrate, wherein the substrate comprises a ceramic selected from aluminum nitride, aluminum oxide, silicon carbide, silicon oxynitride, and combinations thereof; and
C) thereafter contacting the polymeric material and the substrate;
thereby creating adhesion of the polymeric material and the substrate.

30. canceled.

31. (currently amended) A method comprising:
a) plasma treatment of a polymeric material,
b) plasma treatment of a substrate,
c) plasma treatment of a semiconductor,

d) contacting the polymeric material and the substrate, and
e) contacting the semiconductor and the polymeric material;
thereby creating adhesion of the substrate and the polymeric material, and the
polymeric material and the semiconductor.

32. (currently amended) The method of claim 3031, wherein steps a), b), c), d), and e) are carried out in an order selected from: abcde, acbde, abced, acbed, bacde, baced, bcade, bcaed, cabde, cabed, cbade, cbaed, abdce, badce, acebd, caebd, abdace, badace, abdcae, badcae, aceabd, caeabd, acebad, or caebad.

33. (currently amended) The method of claim 3031, wherein steps a), b) and c) are carried out concurrently, and thereafter steps d) and e) are carried out in any order.

34. (currently amended) The method of claim 3031, wherein steps a), b) and c) are carried out in any order, and thereafter steps d) and e) are carried out concurrently.

35. (currently amended) The method of claim 3031, wherein steps a), b), and c) are carried out concurrently, and thereafter steps d) and e) are carried out concurrently.

36. canceled.

37. canceled.